

DDR4 SDRAM VLP RDIMM Addendum

MTA18ADF4G72PZ – 32GB

Features

Information provided here is in addition to or supersedes information provided in the Micron DDR4 RDIMM Core data sheet.

- DDR4 functionality and operations supported as defined in the component data sheet
- Features and specifications defined in the Micron DDR4 RDIMM core data sheet
- 288-pin, very low profile registered dual in-line memory module (VLP RDIMM)
- Fast data transfer rate: PC4-3200, PC4-2933
- 32GB (4 Gig x 72)
- Single-rank
- 16 internal banks; 4 groups of 4 banks each

Figure 1: 288-Pin VLP RDIMM (R/C-F1, PCB 2718)

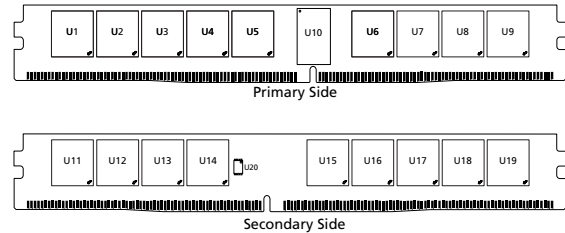
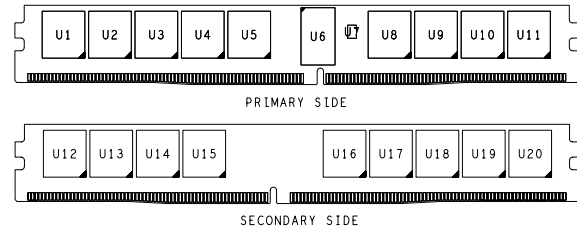


Figure 2: 288-Pin VLP RDIMM (R/C-F2, PCB 2954)



Options

- Operating temperature
 - Commercial ($0^{\circ}\text{C} \leq T_{\text{OPER}} \leq 95^{\circ}\text{C}$)
- Package
 - 288-pin DIMM (Green)
- Frequency/CAS latency
 - 0.625ns @ CL = 22 (DDR4-3200)
 - 0.682ns @ CL = 21 (DDR4-2933)

Marking

None
Z
-3G2
-2G9

Table 1: Addressing

Parameter	32GB
Row address	256K A[17:0]
Column address	1K A[9:0]
Device bank group address	4 BG[1:0]
Device bank address per group	4 BA[1:0]
Device configuration	16Gb (4 Gig x 4), 16 banks
Module rank address	1 CS_n[0]



32GB (x72, ECC, SR) 288-Pin DDR4 VLP RDIMM Features

Table 2: Part Numbers and Timing Parameters – 32GB Modules

Base device: MT40A4G4,¹ 16Gb DDR4 SDRAM

Part Number ²	Module Density	Configuration	Module Bandwidth	Memory Clock/ Data Rate	Clock Cycles (CL _{-n} RCD _{-n} RP)
MTA18ADF4G72PZ-3G2__	32GB	4 Gig x 72	25.6 GB/s	0.625ns/3200 MT/s	22-22-22
MTA18ADF4G72PZ-2G9__	32GB	4 Gig x 72	23.47 GB/s	0.625ns/2933 MT/s	21-21-21

- Notes: 1. The data sheet for the base device can be found on micron.com.
2. All part numbers end with a two-place code (not shown) that designates component and PCB revisions. Consult factory for current revision codes. Example: MTA18ADF4G72PZ-3G2F1.



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DQ Map

Table 3: Component-to-Module DQ Map - PCB 2718

Component Reference Number	Component DQ	Module DQ	Module Pin Number	Component Reference Number	Component DQ	Module DQ	Module Pin Number
U1	0	7	155	U2	0	15	166
	1	5	148		1	13	159
	2	6	10		2	14	21
	3	4	3		3	12	14
U3	0	23	177	U4	0	31	188
	1	21	170		1	29	181
	2	22	32		2	30	43
	3	20	25		3	28	36
U5	0	CB7	199	U6	0	39	247
	1	CB5	192		1	37	240
	2	CB6	54		2	38	102
	3	CB4	47		3	36	95
U7	0	47	258	U8	0	55	269
	1	45	251		1	53	262
	2	46	113		2	54	124
	3	44	106		3	52	117
U9	0	63	280	U11	0	56	130
	1	60	128		1	58	137
	2	62	135		2	57	275
	3	61	273		3	59	282
U12	0	48	119	U13	0	40	108
	1	50	126		1	42	115
	2	49	264		2	41	253
	3	51	271		3	43	260
U14	0	32	97	U15	0	CB1	194
	1	34	104		1	CB3	201
	2	33	242		2	CB0	49
	3	35	249		3	CB2	56
U16	0	25	183	U17	0	17	172
	1	27	190		1	19	179
	2	24	38		2	16	27
	3	26	45		3	18	34
U18	0	9	161	U19	0	1	150
	1	11	168		1	3	157
	2	8	16		2	0	5
	3	10	23		3	2	12



32GB (x72, ECC, SR) 288-Pin DDR4 VLP RDIMM DQ Map

Table 4: Component-to-Module DQ Map - PCB 2954

Component Reference Number	Component DQ	Module DQ	Module Pin Number	Component Reference Number	Component DQ	Module DQ	Module Pin Number
U1	0	6	10	U2	0	14	21
	1	4	3		1	13	159
	2	7	155		2	15	166
	3	5	148		3	12	14
U3	0	22	32	U4	0	30	43
	1	21	170		1	28	36
	2	23	177		2	31	188
	3	20	25		3	29	181
U5	0	CB6	54	U8	0	39	247
	1	CB4	47		1	37	240
	2	CB7	199		2	38	102
	3	CB5	192		3	36	95
U9	0	47	258	U10	0	55	269
	1	45	251		1	53	262
	2	46	113		2	54	124
	3	44	106		3	52	117
U11	0	62	135	U12	0	56	130
	1	61	273		1	59	282
	2	63	280		2	57	275
	3	60	128		3	58	137
U13	0	48	119	U14	0	41	253
	1	51	271		1	43	260
	2	49	264		2	40	108
	3	50	126		3	42	115
U15	0	33	242	U16	0	CB0	49
	1	35	249		1	CB2	56
	2	32	97		2	CB1	194
	3	34	104		3	CB3	201
U17	0	24	38	U18	0	16	27
	1	26	45		1	18	34
	2	25	183		2	17	172
	3	27	190		3	19	179
U19	0	8	16	U20	0	0	5
	1	10	23		1	3	157
	2	9	161		2	1	150
	3	11	168		3	2	12



I_{DD} Specifications

Table 5: DDR4 I_{DD} Specifications and Conditions (0° ≤ T_C ≤ 85°) – 32GB (Die Revision B)

Values are for the MT40A4G4 DDR4 SDRAM only and are computed from values specified in the 16Gb (4 Gig x 4) component data sheet

Parameter	Symbol	3200	2933	Units
One bank ACTIVATE-PRECHARGE current	I _{DD0}	1080	1062	mA
One bank ACTIVATE-PRECHARGE, word line boost, I _{pp} current	I _{pp0}	72	72	mA
One bank ACTIVATE-READ-PRECHARGE current	I _{DD1}	1260	1242	mA
Precharge standby current	I _{DD2N}	936	918	mA
Precharge standby ODT current	I _{DD2NT}	1008	990	mA
Precharge power-down current	I _{DD2P}	774	774	mA
Precharge quiet standby current	I _{DD2Q}	846	846	mA
Active standby current	I _{DD3N}	1404	1386	mA
Active standby I _{pp} current	I _{pp3N}	54	54	mA
Active power-down current	I _{DD3P}	1242	1224	mA
Burst read current	I _{DD4R}	3096	2952	mA
Burst write current	I _{DD4W}	2952	2826	mA
Burst refresh current (1x REF)	I _{DD5R}	1458	1404	mA
Burst refresh I _{pp} current (1x REF)	I _{pp5R}	90	90	mA
Self refresh current: Normal temperature range (0°C to 85°C)	I _{DD6N (0-85°C)}	1206	1206	mA
Self refresh current: Extended temperature range (0°C to 95°C)	I _{DD6E (0-95°C)}	2178	2178	mA
Self refresh current: Reduced temperature range (0°C to 45°C)	I _{DD6R (0-45°C)}	522	522	mA
Auto self refresh current (25°C)	I _{DD6A (25°C)}	180	180	mA
Auto self refresh current (45°C)	I _{DD6A (45°C)}	522	522	mA
Auto self refresh current (75°C)	I _{DD6A (75°C)}	1098	1098	mA
Auto self refresh current (95°C)	I _{DD6A (95°C)}	2178	2178	mA
Auto self refresh I _{pp} current	I _{pp6X}	198	198	mA
Bank interleave read current	I _{DD7}	4284	4158	mA
Bank interleave read I _{pp} current	I _{pp7}	198	198	mA
Maximum power-down current	I _{DD8}	720	720	mA

Notes: 1. When T_C > 85°C, the I_{DD} and I_{pp} values must be derated. Refer to the base device data sheet I_{DD} and I_{pp} specification tables for derating values for the applicable die-revision.



32GB (x72, ECC, SR) 288-Pin DDR4 VLP RDIMM I_{DD} Specifications

Table 6: DDR4 I_{DD} Specifications and Conditions (0° ≤ T_C ≤ 85°) – 32GB (Die Revision F)

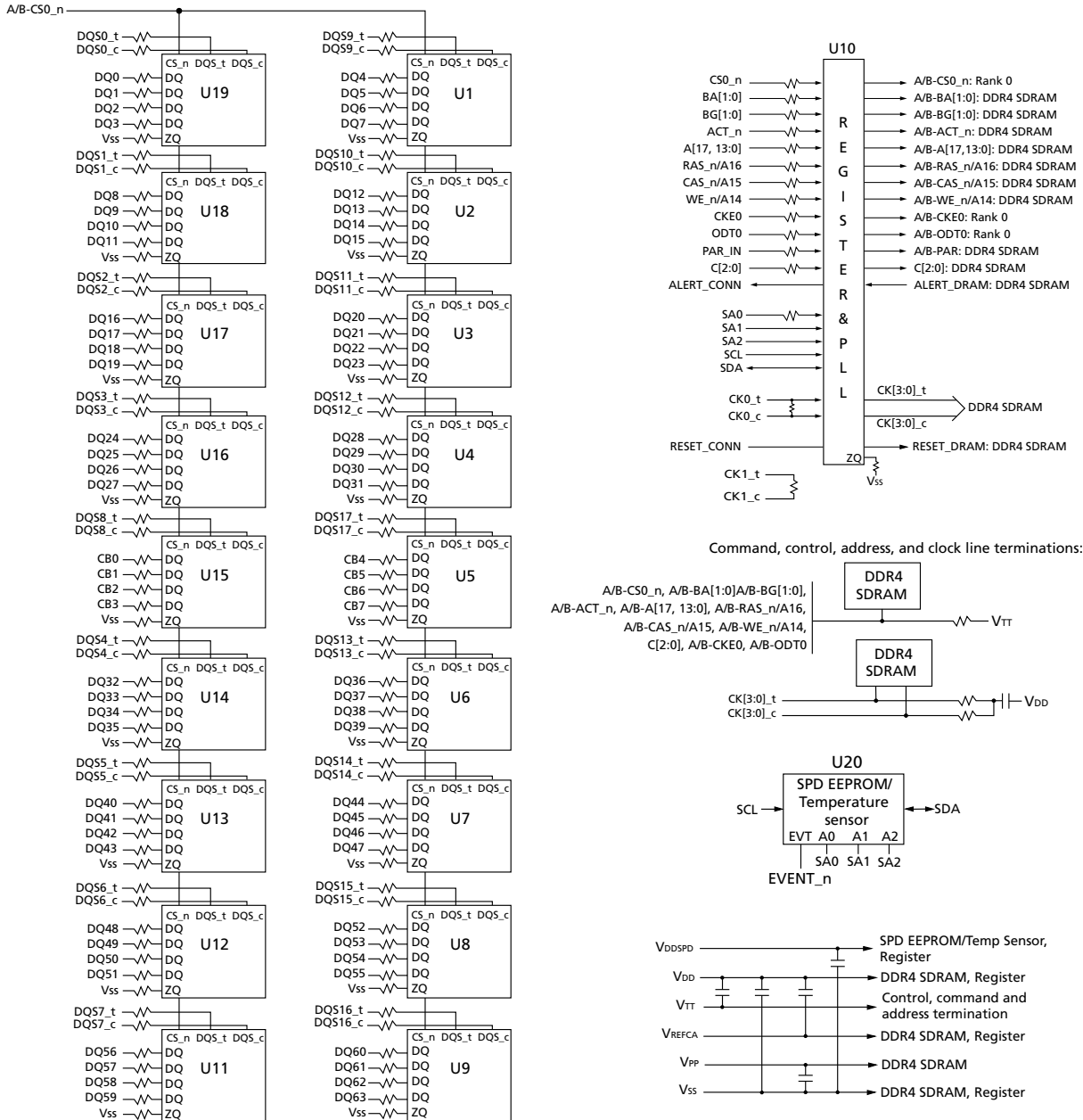
Values are for the MT40A4G4 DDR4 SDRAM only and are computed from values specified in the 16Gb (4 Gig x 4) component data sheet

Parameter	Symbol	3200	2933	Units
One bank ACTIVATE-PRECHARGE current	I _{DD0}	882	873	mA
One bank ACTIVATE-PRECHARGE, word line boost, I _{pp} current	I _{pp0}	45	45	mA
One bank ACTIVATE-READ-PRECHARGE current	I _{DD1}	981	972	mA
Precharge standby current	I _{DD2N}	810	792	mA
Precharge standby ODT current	I _{DD2NT}	801	792	mA
Precharge power-down current	I _{DD2P}	684	684	mA
Precharge quiet standby current	I _{DD2Q}	756	756	mA
Active standby current	I _{DD3N}	1098	1080	mA
Active standby I _{pp} current	I _{pp3N}	36	36	mA
Active power-down current	I _{DD3P}	900	882	mA
Burst read current	I _{DD4R}	1602	1530	mA
Burst write current	I _{DD4W}	1350	1305	mA
Burst refresh current (1x REF)	I _{DD5R}	954	954	mA
Burst refresh I _{pp} current (1x REF)	I _{pp5R}	54	54	mA
Self refresh current: Normal temperature range (0°C to 85°C)	I _{DD6N (0-85°C)}	954	954	mA
Self refresh current: Extended temperature range (0°C to 95°C)	I _{DD6E (0-95°C)}	1620	1620	mA
Self refresh current: Reduced temperature range (0°C to 45°C)	I _{DD6R (0-45°C)}	360	360	mA
Auto self refresh current (25°C)	I _{DD6A (25°C)}	198	198	mA
Auto self refresh current (45°C)	I _{DD6A (45°C)}	360	360	mA
Auto self refresh current (75°C)	I _{DD6A (75°C)}	918	918	mA
Auto self refresh current (95°C)	I _{DD6A (95°C)}	1620	1620	mA
Auto self refresh I _{pp} current	I _{pp6X}	108	108	mA
Bank interleave read current	I _{DD7}	1845	1827	mA
Bank interleave read I _{pp} current	I _{pp7}	144	144	mA
Maximum power-down current	I _{DD8}	648	648	mA

Notes: 1. When T_C > 85°C, the I_{DD} and I_{pp} values must be derated. Refer to the base device data sheet I_{DD} and I_{pp} specification tables for derating values for the applicable die-revision.

Functional Block Diagram

Figure 3: Functional Block Diagram



Note: 1. The ZQ ball on each DDR4 component is connected to an external $240\Omega \pm 1\%$ resistor that is tied to ground. It is used for the calibration of the component's ODT and output driver.

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